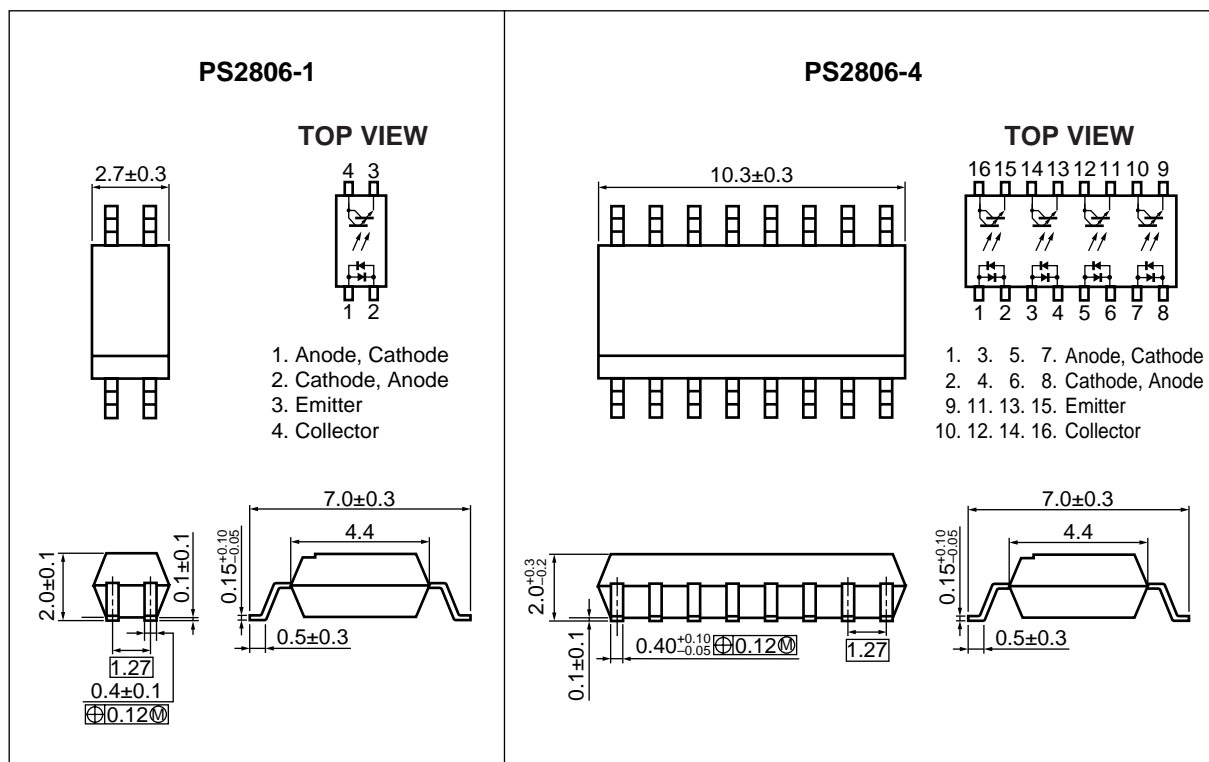
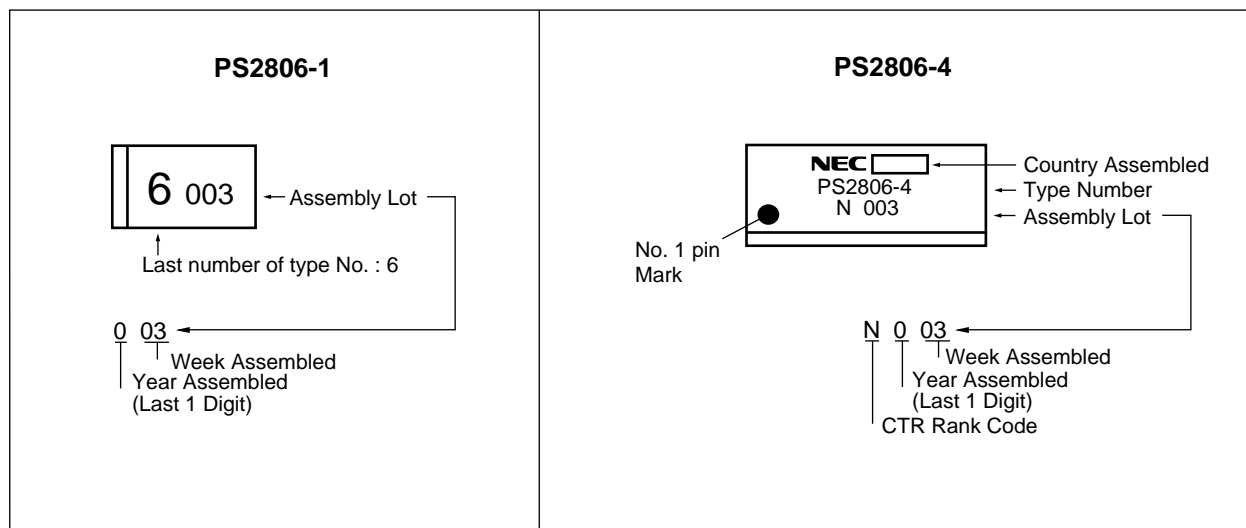


★ PACKAGE DIMENSIONS (UNIT: mm)



MARKING



ORDERING INFORMATION (Solder Contains Lead)

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS2806-1	4-pin SOP	50 pcs (Tape 50 pcs cut)	PS2806-1
PS2806-1-F3		Embossed Tape 3 500 pcs/reel	
PS2806-1-F4			
PS2806-4	16-pin SOP	Magazine Case 45 pcs	PS2806-4
PS2806-4-F3		Embossed Tape 2 500 pcs/reel	
PS2806-4-F4			

*1 For the application of the Safety Standard, following part number should be used.

ORDERING INFORMATION (Pb-Free)

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS2806-1-A	4-pin SOP	50 pcs (Tape 50 pcs cut)	PS2806-1
PS2806-1-F3-A		Embossed Tape 3 500 pcs/reel	
PS2806-1-F4-A			
PS2806-4-A	16-pin SOP	Magazine Case 45 pcs	PS2806-4
PS2806-4-F3-A		Embossed Tape 2 500 pcs/reel	
PS2806-4-F4-A			

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2806-1	PS2806-4	
Diode	Forward Current (DC)	I_F	± 50		mA
	Power Dissipation Derating	$\Delta P_D/^{\circ}\text{C}$	0.6	0.8	mW/ $^{\circ}\text{C}$
	Power Dissipation	P_D	60	80	mW/ch
	Peak Forward Current ^{*1}	I_{FP}	± 1		A
Transistor	Collector to Emitter Voltage	V_{CEO}	40		V
	Emitter to Collector Voltage	V_{ECO}	6		V
	Collector Current	I_C	90	100	mA/ch
	Power Dissipation Derating	$\Delta P_C/^{\circ}\text{C}$	1.2		mW/ $^{\circ}\text{C}$
	Power Dissipation	P_C	120		mW/ch
Isolation Voltage ^{*2}		BV	2 500		Vr.m.s.
Operating Ambient Temperature		T_A	-55 to +100		$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-55 to +150		$^{\circ}\text{C}$

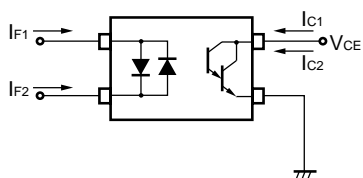
*1 PW = 100 μs , Duty Cycle = 1 %

*2 AC voltage for 1 minute at $T_A = 25\text{ }^{\circ}\text{C}$, RH = 60 % between input and output

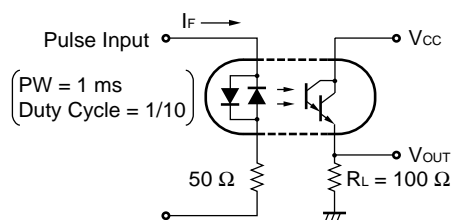
ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = \pm 5\text{ mA}$		1.1	1.4	V
	Terminal Capacitance	C_t	$V = 0\text{ V}, f = 1.0\text{ MHz}$		30		pF
Transistor	Collector to Emitter Dark Current	I_{CEO}	$V_{CE} = 40\text{ V}, I_F = 0\text{ mA}$			400	nA
Coupled	Current Transfer Ratio (I_C/I_F)	CTR	$I_F = \pm 1\text{ mA}, V_{CE} = 2\text{ V}$	200	2 000		%
	CTR Ratio *1	CTR1/CTR2	$I_F = 1\text{ mA}, V_{CE} = 2\text{ V}$	0.3	1.0	3.0	
	Collector Saturation Voltage	$V_{CE(sat)}$	$I_F = \pm 1\text{ mA}, I_C = 2\text{ mA}$			1.0	V
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1.0\text{ kV}_{DC}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0\text{ V}, f = 1.0\text{ MHz}$		0.4		pF
	Rise Time *2	t_r	$V_{CC} = 5\text{ V}, I_C = 2\text{ mA}, R_L = 100\ \Omega$		200		μs
	Fall Time *2	t_f			200		

*1 $CTR1 = I_{C1}/I_{F1}$, $CTR2 = I_{C2}/I_{F2}$

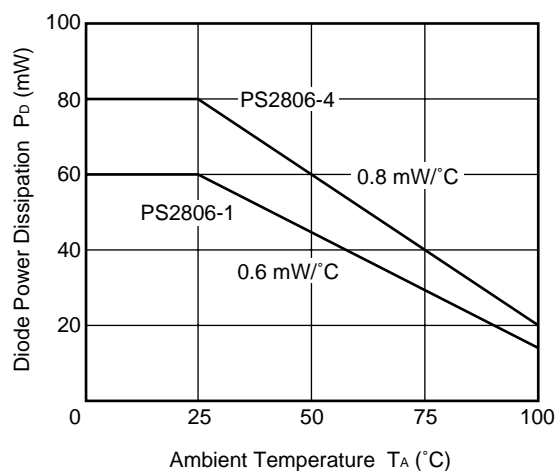


*2 Test circuit for switching time

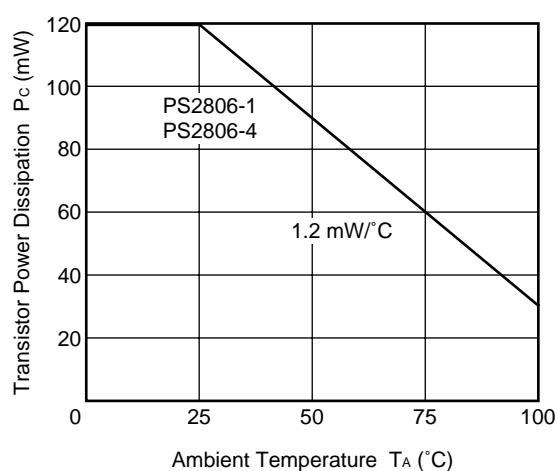


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

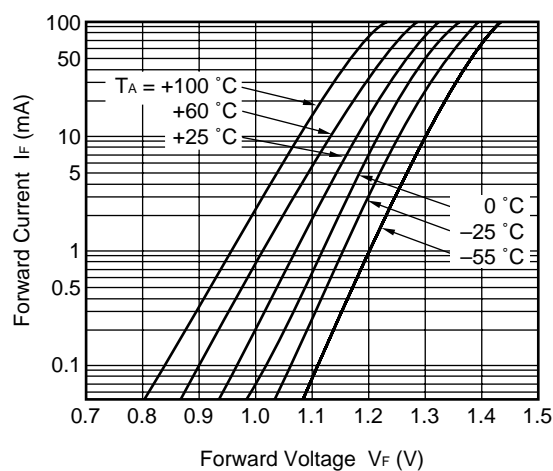
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



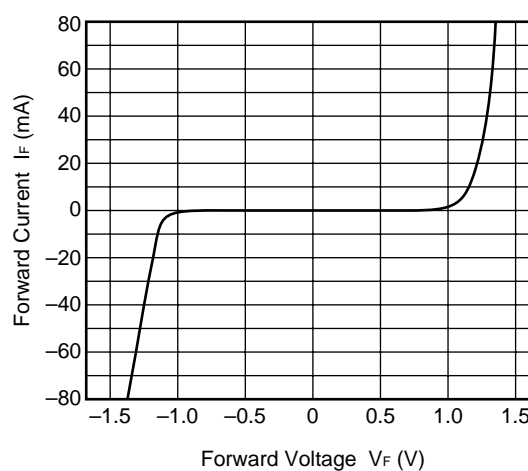
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



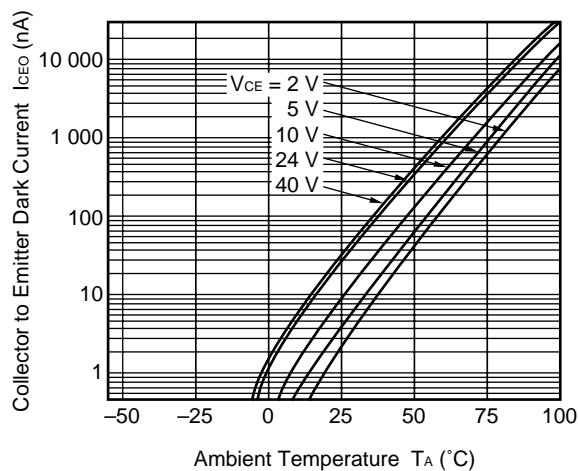
FORWARD CURRENT vs. FORWARD VOLTAGE



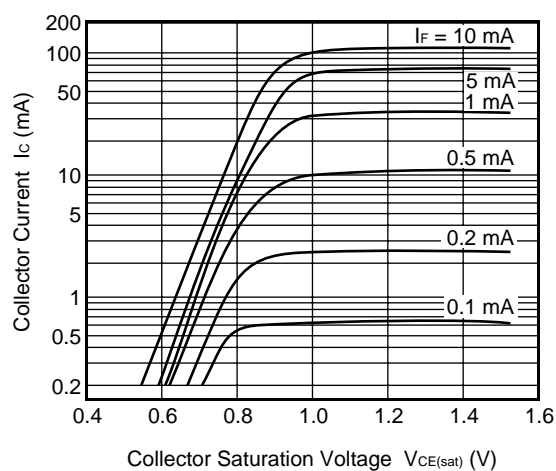
FORWARD CURRENT vs. FORWARD VOLTAGE

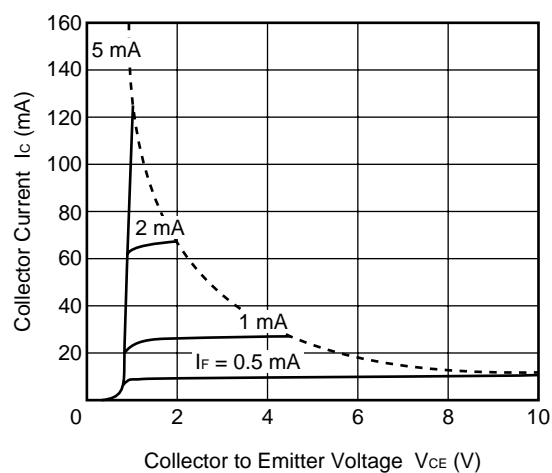
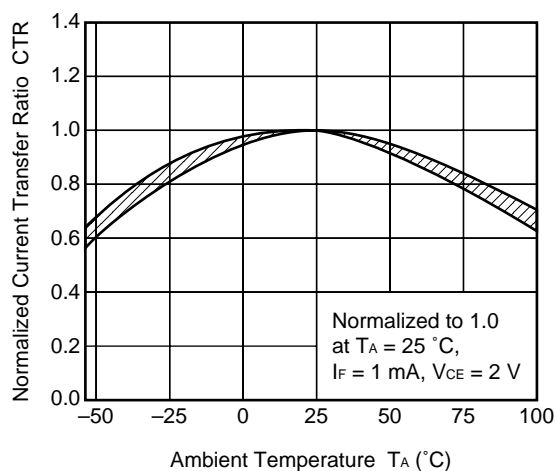
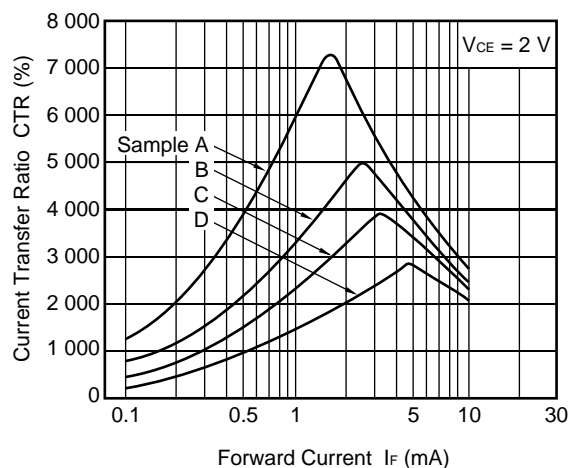
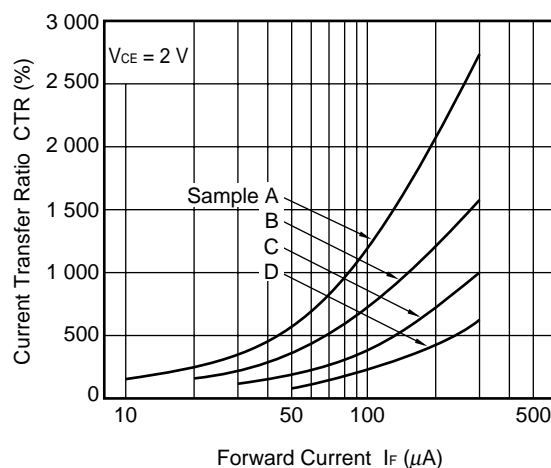
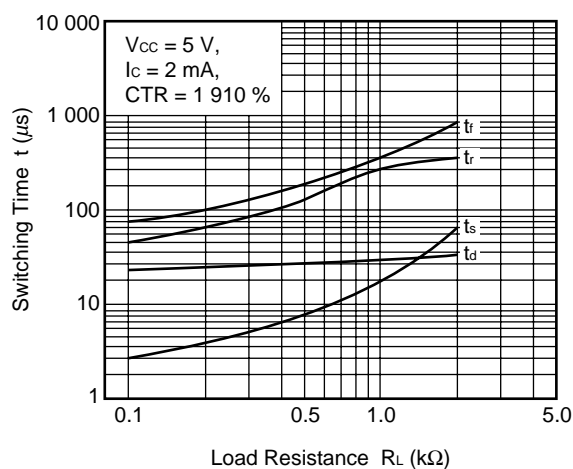
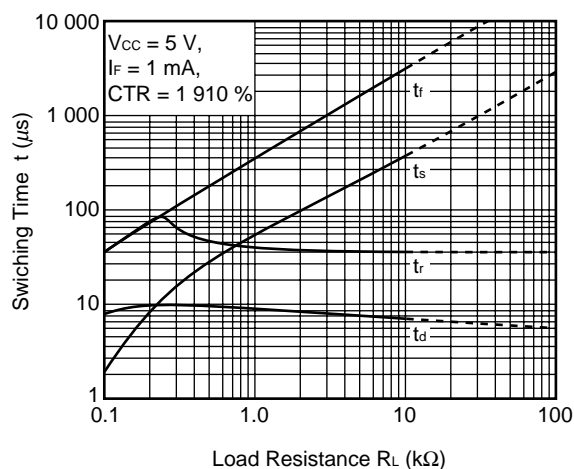


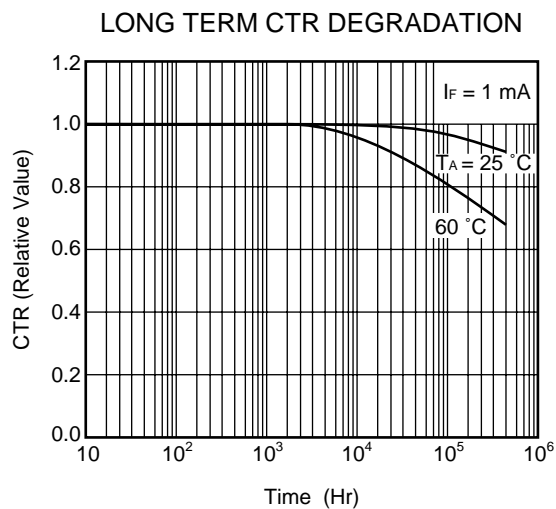
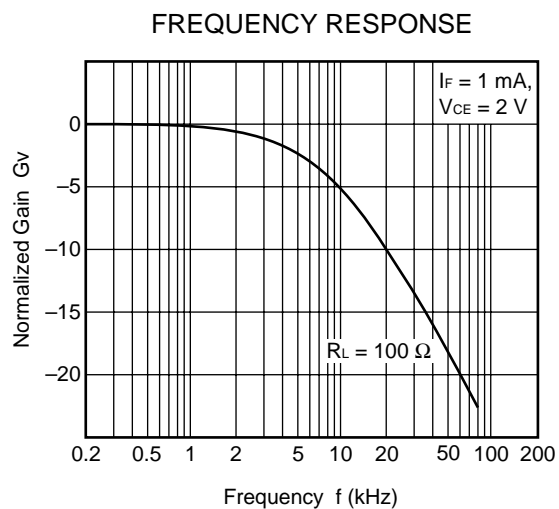
COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE



COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE



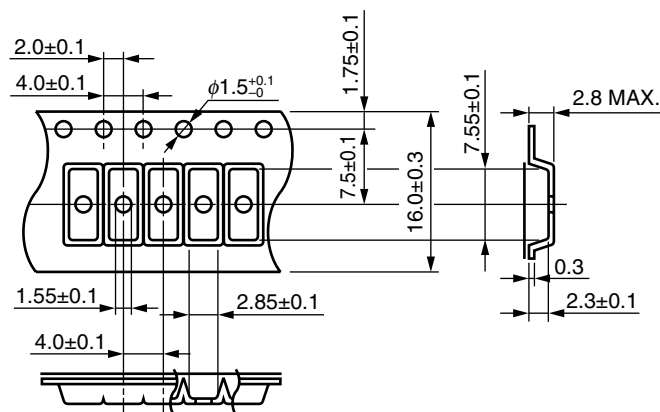
COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGENORMALIZED CURRENT TRANSFER
RATIO vs. AMBIENT TEMPERATURECURRENT TRANSFER RATIO vs.
FORWARD CURRENTCURRENT TRANSFER RATIO vs.
FORWARD CURRENTSWITCHING TIME vs.
LOAD RESISTANCESWITCHING TIME vs.
LOAD RESISTANCE



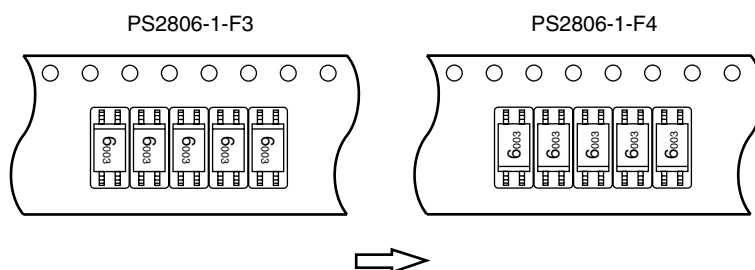
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

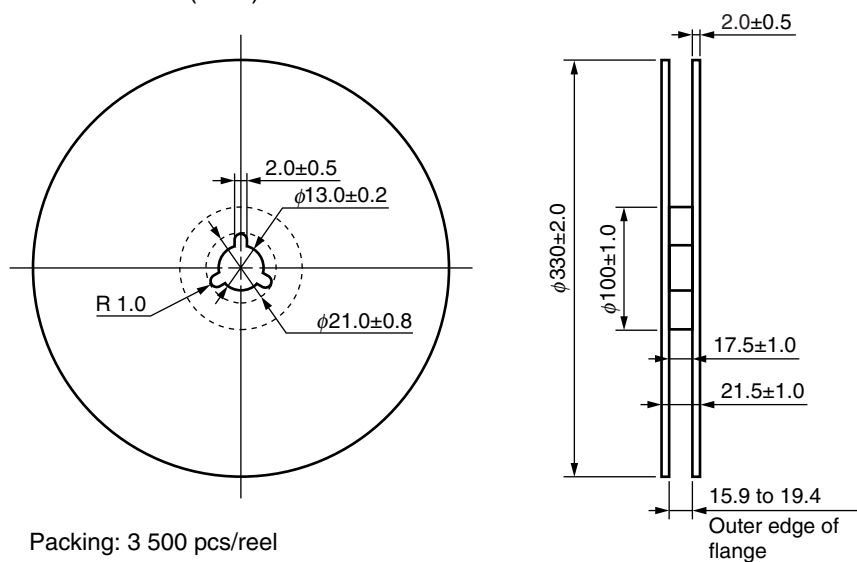
Outline and Dimensions (Tape)



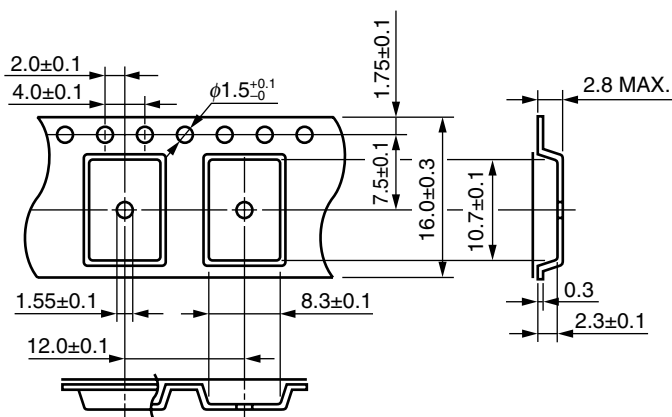
Tape Direction



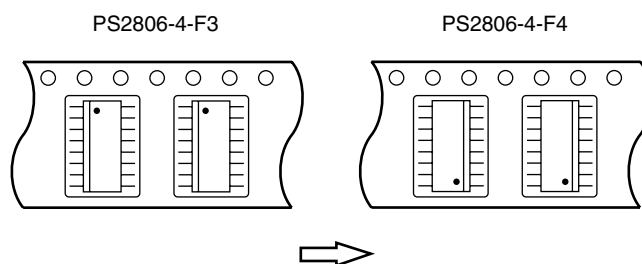
Outline and Dimensions (Reel)



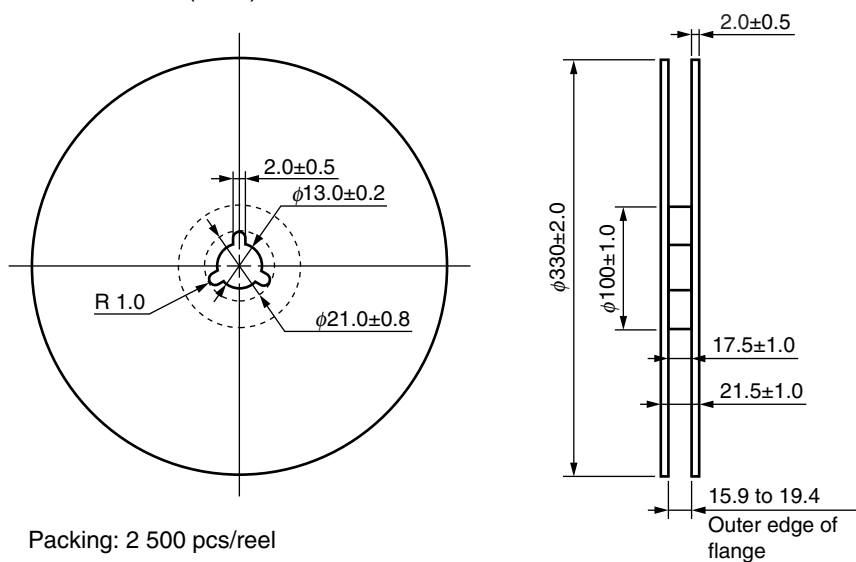
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



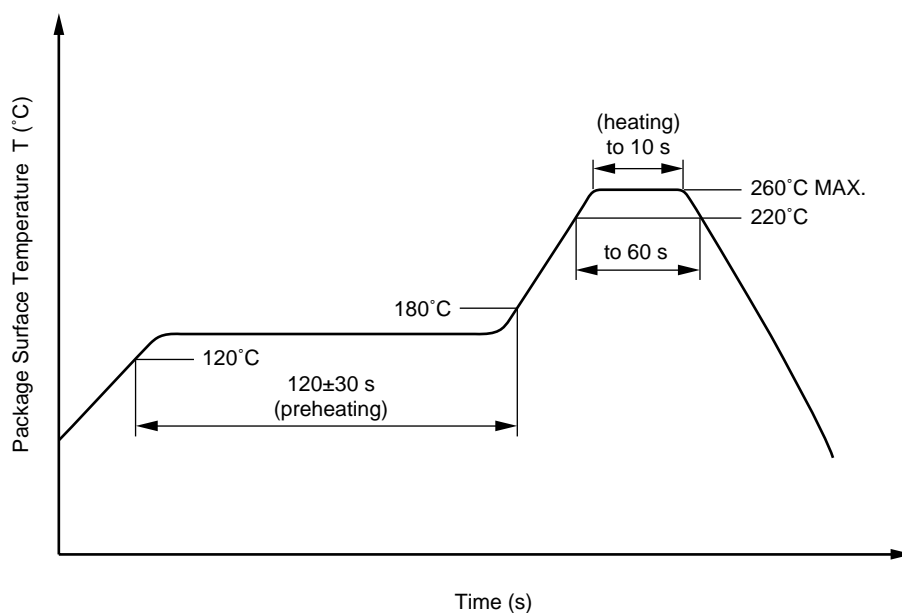
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

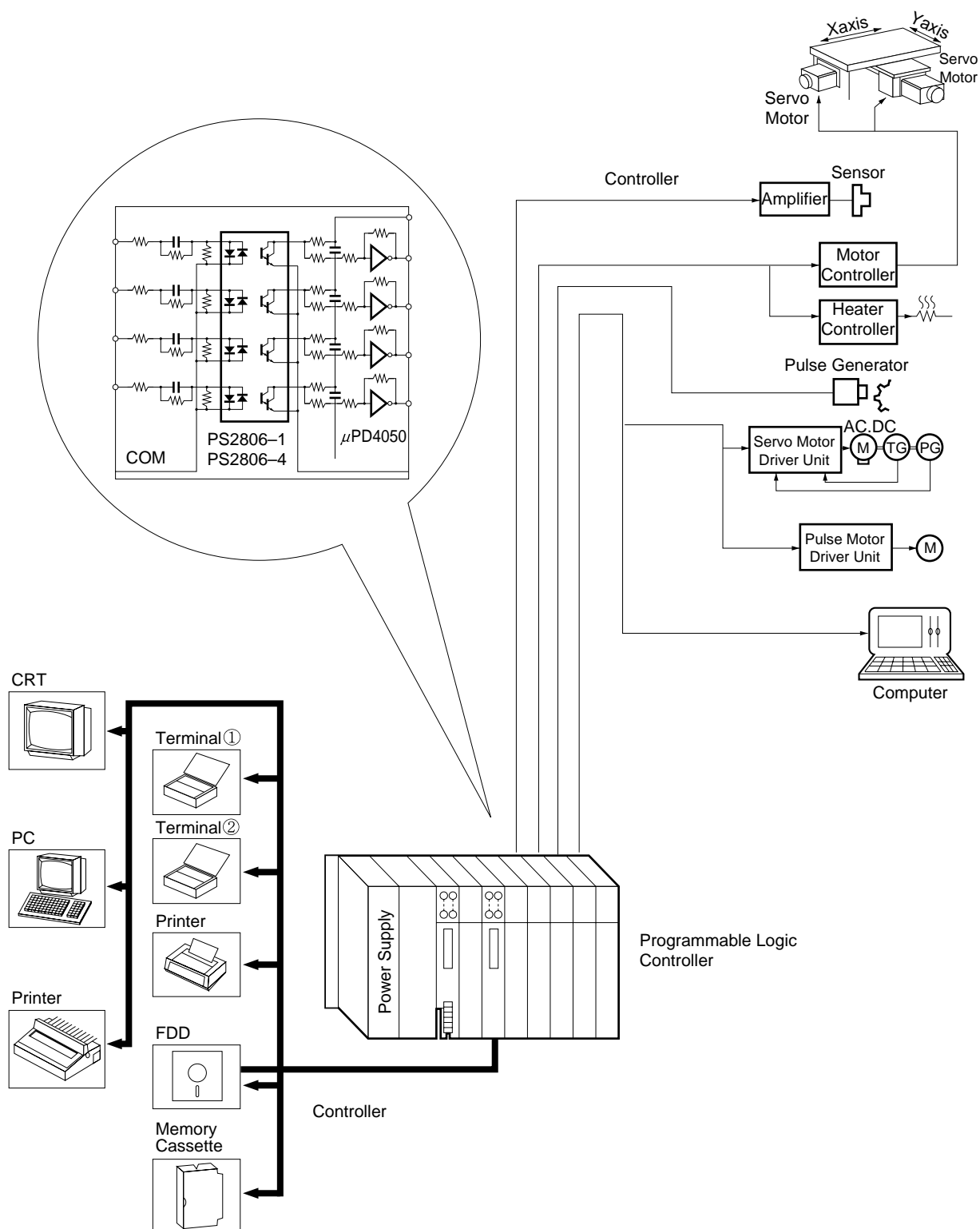
Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

PROGRAMMABLE LOGIC CONTROLLERS EXAMPLE

Purpose: In-out interface



Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices	
		-A	-AZ
Lead (Pb)	< 1000 PPM	Not Detected	(*)
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

Important Information and Disclaimer: Information provided by CEL on its website or in other communications concerning the substance content of its products represents knowledge and belief as of the date that it is provided. CEL bases its knowledge and belief on information provided by third parties and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. CEL has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. CEL and CEL suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall CEL's liability arising out of such information exceed the total purchase price of the CEL part(s) at issue sold by CEL to customer on an annual basis.

See CEL Terms and Conditions for additional clarification of warranties and liability.